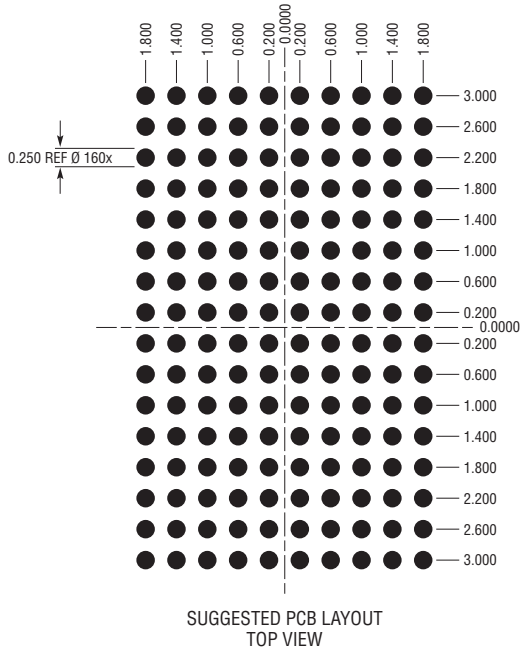
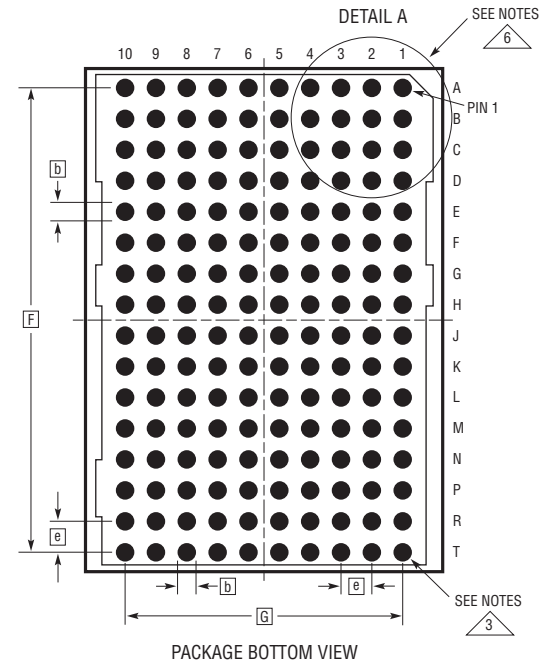
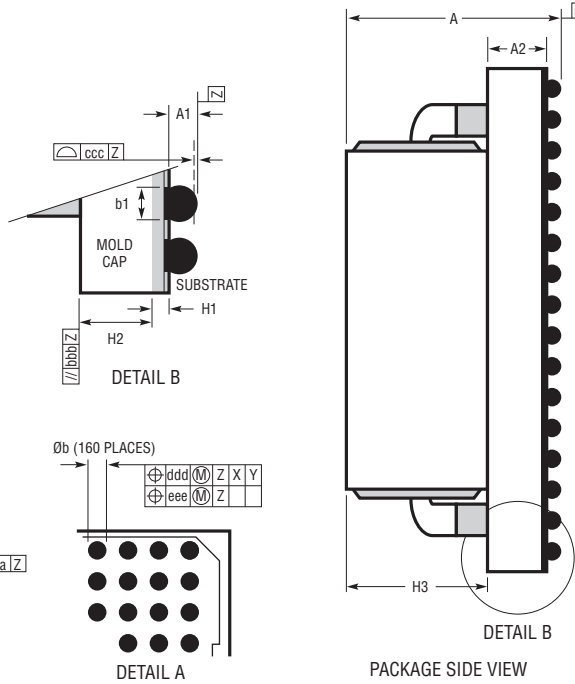
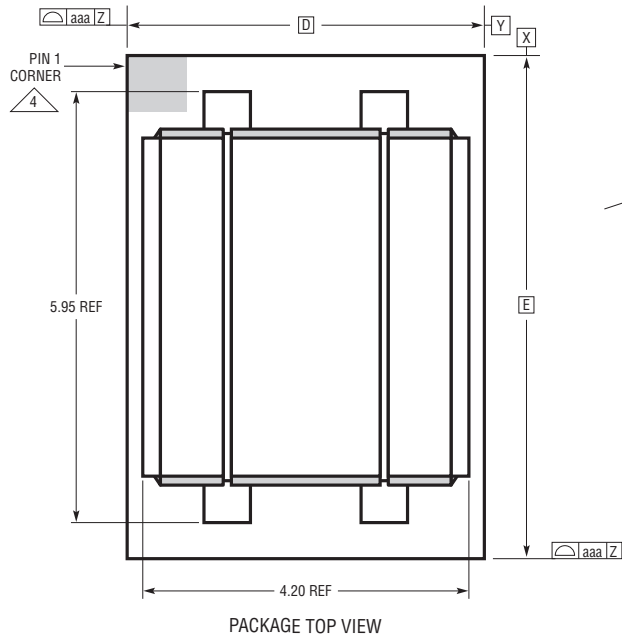


**BGA Package**  
**160-Lead (6.55mm × 4.65mm × 3.585mm)**  
 (Reference LTC DWG # 05-08-7104 Rev 0)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	3.26	3.585	3.91	
A1	0.13	0.19	0.25	BALL HT
A2	1.13	1.22	1.31	
b	0.20	0.25	0.30	BALL DIMENSION
b1	0.20	0.23	0.26	PAD DIMENSION
D		4.65		
E		6.55		
e		0.40		
F		6.00		
G		3.60		
H1		0.32 REF		SUBSTRATE THK
H2		0.90 REF		MOLD CAP HT
H3	2.00	2.175	2.35	INDUCTOR HT
aaa			0.10	
bbb			0.10	
ccc			0.08	
ddd			0.15	
eee			0.05	

TOTAL NUMBER OF BALLS: 160

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JEP95

4 DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

